Abstracts

60 GHz flip-chip assembled MIC design considering chip-substrate effect

Y. Arai, M. Sato, H.T. Yamada, T. Hamada, K. Nagai and H.I. Fujishiro. "60 GHz flip-chip assembled MIC design considering chip-substrate effect." 1997 MTT-S International Microwave Symposium Digest 2. (1997 Vol. II [MWSYM]): 447-450.

In this paper, a 60 GHz MICs with flip-chip assembled pseudomorphic-HEMT is demonstrated. With electromagnetic field analysis, the assembly effect was estimated. An amplifier has a gain of 13 dB and a 30/60 GHz frequency doubler has a gain of -3 dB. Measured and simulated results clarify the potential of the structure and design method.

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